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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	6000
Total RAM Bits	73728
Number of I/O	100
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp6e-5t144c

Slice

Each slice contains two LUT4 lookup tables feeding two registers (programmed to be in FF or Latch mode), and some associated logic that allows the LUTs to be combined to perform functions such as LUT5, LUT6, LUT7 and LUT8. There is control logic to perform set/reset functions (programmable as synchronous/asynchronous), clock select, chip-select and wider RAM/ROM functions. Figure 2-3 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge/level clocks.

There are 14 input signals: 13 signals from routing and one from the carry-chain (from adjacent slice or PFU). There are 7 outputs: 6 to routing and one to carry-chain (to adjacent PFU). Table 2-1 lists the signals associated with each slice.

Figure 2-3. Slice Diagram

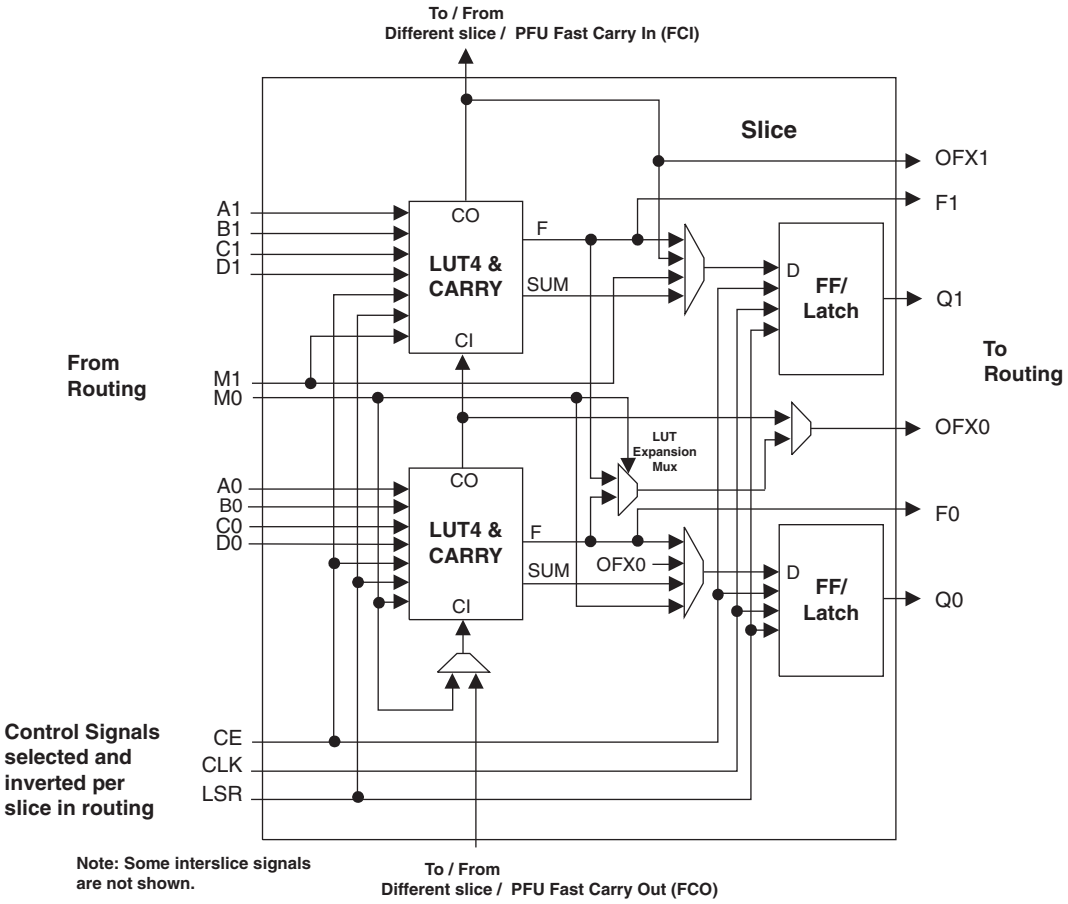
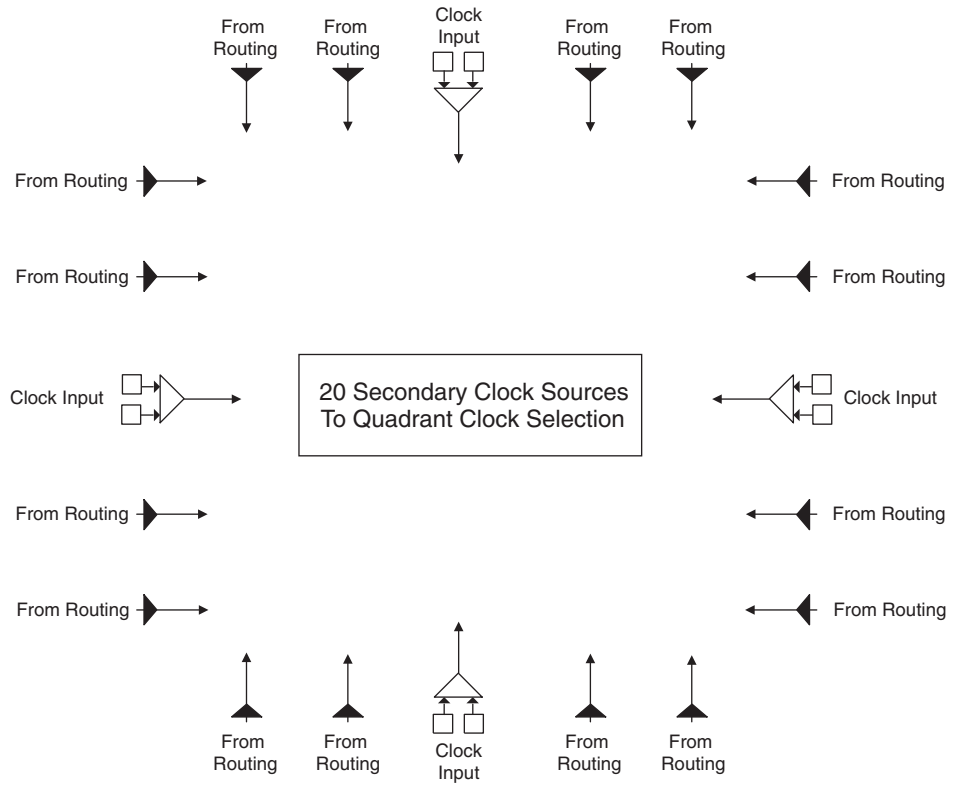


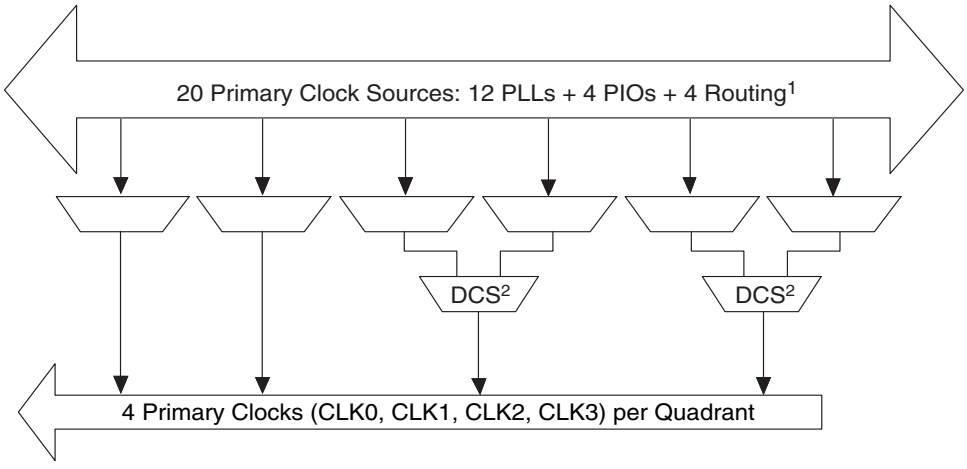
Figure 2-6. Secondary Clock Sources



Clock Routing

The clock routing structure in LatticeXP devices consists of four Primary Clock lines and a Secondary Clock network per quadrant. The primary clocks are generated from MUXs located in each quadrant. Figure 2-7 shows this clock routing. The four secondary clocks are generated from MUXs located in each quadrant as shown in Figure 2-8. Each slice derives its clock from the primary clock lines, secondary clock lines and routing as shown in Figure 2-9.

Figure 2-7. Per Quadrant Primary Clock Selection



1. Smaller devices have fewer PLL related lines.
2. Dynamic clock select.

For more information on the PLL, please see details of additional technical documentation at the end of this data sheet.

Dynamic Clock Select (DCS)

The DCS is a global clock buffer with smart multiplexer functions. It takes two independent input clock sources and outputs a clock signal without any glitches or runt pulses. This is achieved irrespective of where the select signal is toggled. There are eight DCS blocks per device, located in pairs at the center of each side. Figure 2-12 illustrates the DCS Block Macro.

Figure 2-12. DCS Block Primitive

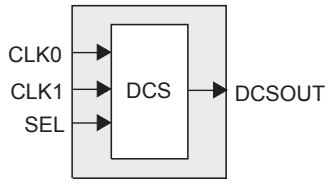
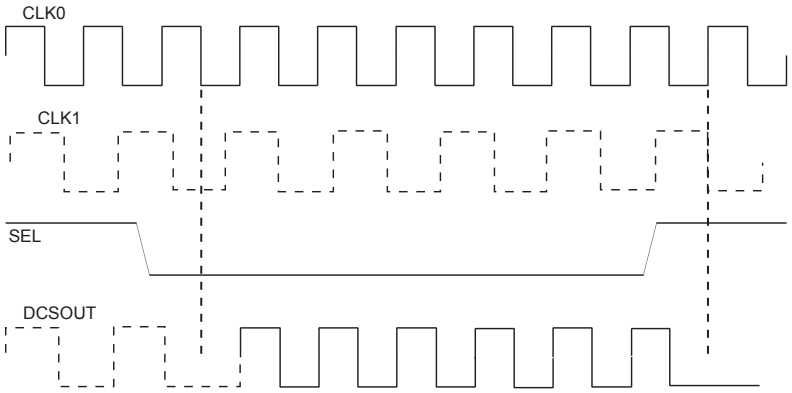


Figure 2-13 shows timing waveforms of the default DCS operating mode. The DCS block can be programmed to other modes. For more information on the DCS, please see details of additional technical documentation at the end of this data sheet.

Figure 2-13. DCS Waveforms



sysMEM Memory

The LatticeXP family of devices contain a number of sysMEM Embedded Block RAM (EBR). The EBR consists of a 9-Kbit RAM, with dedicated input and output registers.

sysMEM Memory Block

The sysMEM block can implement single port, dual port or pseudo dual port memories. Each block can be used in a variety of depths and widths as shown in Table 2-6.

Figure 2-26. DQS Local Bus

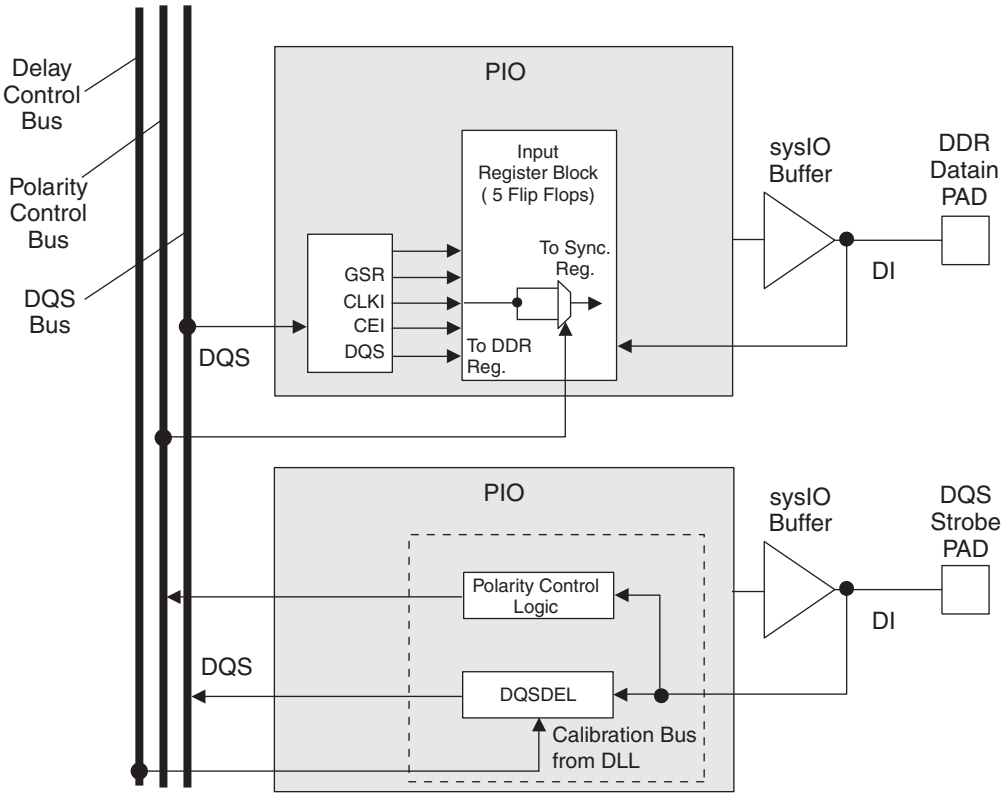


Figure 2-27. DLL Calibration Bus and DQS/DQS Transition Distribution

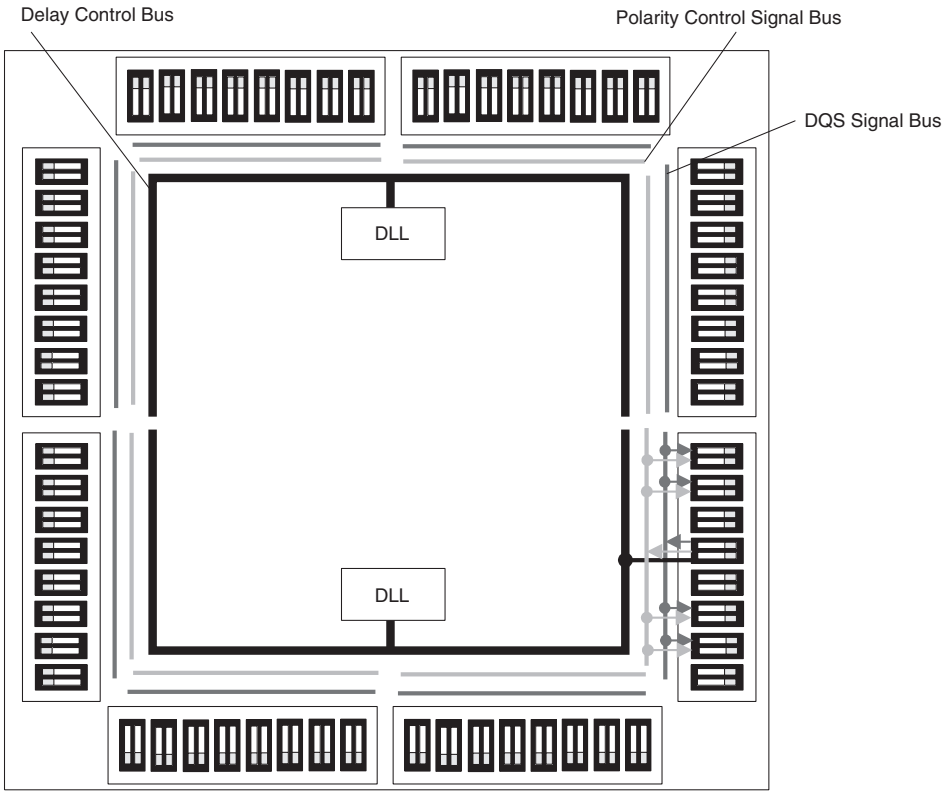
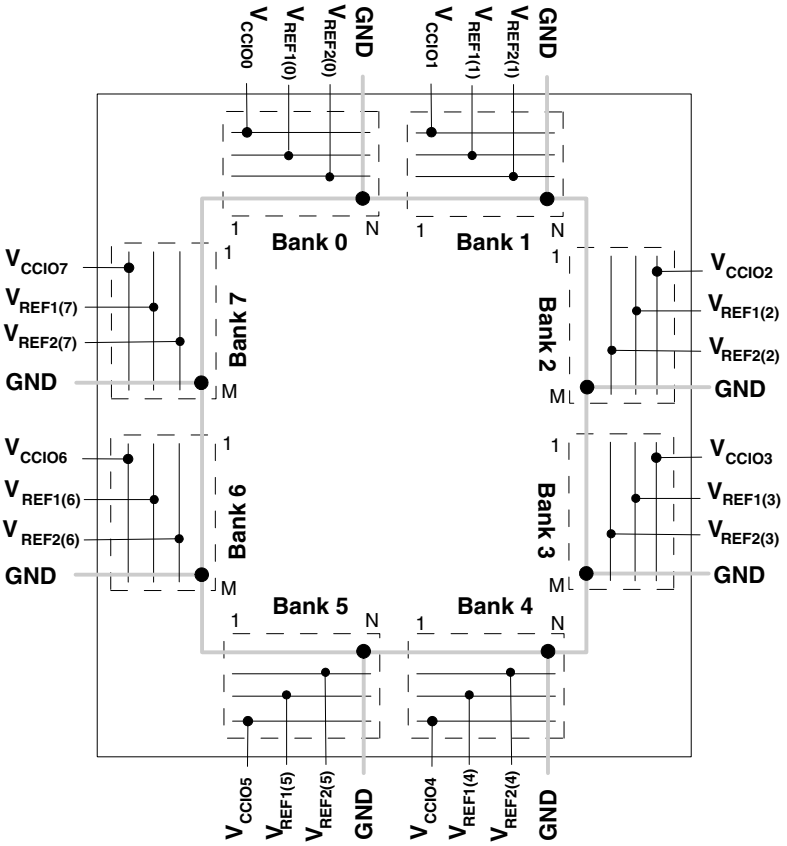


Figure 2-28. LatticeXP Banks



Note: N and M are the maximum number of I/Os per bank.

LatticeXP devices contain two types of sysIO buffer pairs.

1. **Top and Bottom sysIO Buffer Pair (Single-Ended Outputs Only)**
   The sysIO buffer pairs in the top and bottom banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (both ratioed and referenced). The referenced input buffer can also be configured as a differential input.

   The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

   Only the I/Os on the top and bottom banks have PCI clamps. Note that the PCI clamp is enabled after V_{CC}, V_{CCAUX} and V_{CCIO} are at valid operating levels and the device has been configured.

2. **Left and Right sysIO Buffer Pair (Differential and Single-Ended Outputs)**
   The sysIO buffer pairs in the left and right banks of the device consist of two single-ended output drivers, two sets of single-ended input buffers (both ratioed and referenced) and one differential output driver. The referenced input buffer can also be configured as a differential input. In these banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

   Select I/Os in the left and right banks have LVDS differential output drivers. Refer to the Logic Signal Connections tables for more information.

Table 2-9. Characteristics of Normal, Off and Sleep Modes

Characteristic	Normal	Off	Sleep
SLEEPN Pin	High	—	Low
Static Icc	Typical <100mA	0	Typical <100uA
I/O Leakage	<10µA	<1mA	<10µA
Power Supplies VCC/VCCIO/VCCAUX	Normal Range	Off	Normal Range
Logic Operation	User Defined	Non Operational	Non operational
I/O Operation	User Defined	Tri-state	Tri-state
JTAG and Programming circuitry	Operational	Non-operational	Non-operational
EBR Contents and Registers	Maintained	Non-maintained	Non-maintained

SLEEPN Pin Characteristics

The SLEEPN pin behaves as an LVCMOS input with the voltage standard appropriate to the VCC supply for the device. This pin also has a weak pull-up typically in the order of 10µA along with a Schmidt trigger and glitch filter to prevent false triggering. An external pull-up to V_{CC} is recommended when Sleep Mode is not used to ensure the device stays in normal operation mode. Typically the device enters Sleep Mode several hundred ns after SLEEPN is held at a valid low and restarts normal operation as specified in the Sleep Mode Timing table. The AC and DC specifications portion of this data sheet show a detailed timing diagram.

Configuration and Testing

The following section describes the configuration and testing features of the LatticeXP family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeXP devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeXP devices contain two possible ports that can be used for device configuration and programming. The test access port (TAP), which supports serial configuration, and the sysCONFIG port that supports both byte-wide and serial configuration.

The non-volatile memory in the LatticeXP can be configured in three different modes:

- In sysCONFIG mode via the sysCONFIG port. Note this can also be done in background mode.
- In 1532 mode via the 1149.1 port.
- In background mode via the 1149.1 port. This allows the device to be operated while reprogramming takes place.

The SRAM configuration memory can be configured in three different ways:

- At power-up via the on-chip non-volatile memory.
- In 1532 mode via the 1149.1 port SRAM direct configuration.
- In sysCONFIG mode via the sysCONFIG port SRAM direct configuration.

sysIO Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input Voltage		0	—	2.4	V
V_{THD}	Differential Input Threshold		+/-100	—	—	mV
V_{CM}	Input Common Mode Voltage	100mV ≤ V_{THD}	V_{THD}/2	1.2	1.8	V
		200mV ≤ V_{THD}	V_{THD}/2	1.2	1.9	V
		350mV ≤ V_{THD}	V_{THD}/2	1.2	2.0	V
I_{IN}	Input current	Power on or power off	—	—	+/-10	µA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	R_T = 100 ohms	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	R_T = 100 ohms	0.9V	1.03	—	V
V_{OD}	Output voltage differential	(V_{OP} - V_{OM}), R_T = 100 ohms	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	(V_{OP} - V_{OM})/2, R_T = 100 ohms	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	V_{OD} = 0V Driver outputs shorted	—	—	6	mA

Differential HSTL and SSTL

Differential HSTL and SSTL outputs are implemented as a pair of complementary single-ended outputs. All allowable single-ended output classes (class I and class II) are supported in this mode.

LVDS25E

The top and bottom side of LatticeXP devices support LVDS outputs via emulated complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The scheme shown in Figure 3-1 is one possible solution for point-to-point signals.

Figure 3-1. LVDS25E Output Termination Example

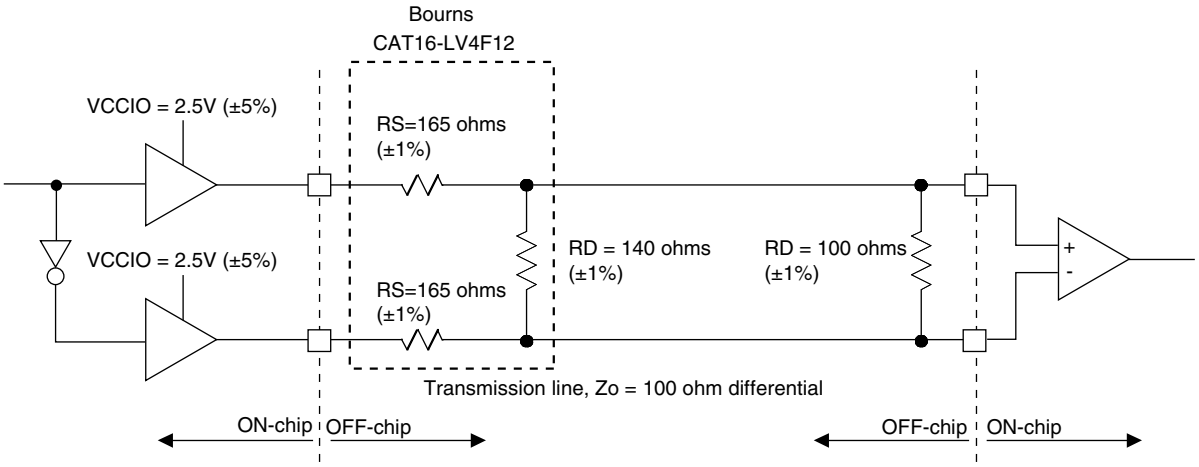


Table 3-1. LVDS25E DC Conditions

Over Recommended Operating Conditions

Parameter	Description	Typical	Units
V_{OH}	Output high voltage	1.43	V
V_{OL}	Output low voltage	1.07	V
V_{OD}	Output differential voltage	0.35	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	100	ohms
I_{DC}	DC output current	3.66	mA

BLVDS

The LatticeXP devices support BLVDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel external resistor across the driver outputs. BLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-2 is one possible solution for bi-directional multi-point differential signals.

Typical Building Block Function Performance[1]

Pin-to-Pin Performance (LVCMOS25 12 mA Drive)

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	6.1	ns
32-bit decoder	7.3	ns
64-bit decoder	8.2	ns
4:1 MUX	4.9	ns
8:1 MUX	5.3	ns
16:1 MUX	5.7	ns
32:1 MUX	6.3	ns

Register to Register Performance

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	351	MHz
32-bit decoder	248	MHz
64-bit decoder	237	MHz
4:1 MUX	590	MHz
8:1 MUX	523	MHz
16:1 MUX	434	MHz
32:1 MUX	355	MHz
8-bit adder	343	MHz
16-bit adder	292	MHz
64-bit adder	130	MHz
16-bit counter	388	MHz
32-bit counter	295	MHz
64-bit counter	200	MHz
64-bit accumulator	164	MHz
Embedded Memory Functions		
Single Port RAM 256x36 bits	254	MHz
True-Dual Port RAM 512x18 bits	254	MHz
Distributed Memory Functions		
16x2 SP RAM	434	MHz
64x2 SP RAM	332	MHz
128x4 SP RAM	235	MHz
32x2 PDP RAM	322	MHz
64x4 PDP RAM	291	MHz

1. These timing numbers were generated using the ispLEVER design tool. Exact performance may vary with design and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

Timing v.F0.11

Derating Logic Timing

Logic timing provided in the following sections of this data sheet and in the ispLEVER design tools are worst case numbers in the operating range. Actual delays at nominal temperature and voltage for best-case process can be much better than the values given in the tables. The ispLEVER design tool from Lattice can provide logic timing numbers at a particular temperature and voltage.

Timing Diagrams

PFU Timing Diagrams

Figure 3-6. Slice Single/Dual Port Write Cycle Timing

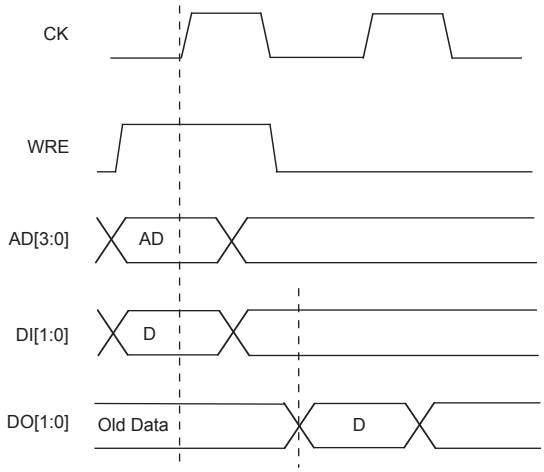
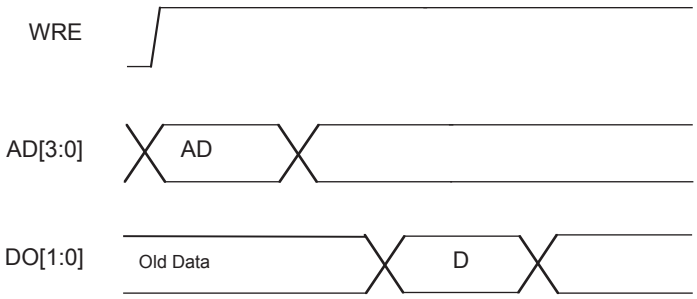


Figure 3-7. Slice Single /Dual Port Read Cycle Timing



PICs and DDR Data (DQ) Pins Associated with the DDR Strobe (DQS) Pin

PICs Associated with DQS Strobe	PIO within PIC	Polarity	DDR Strobe (DQS) and Data (DQ) Pins
P[Edge] [n-4]	A	True	DQ
	B	Complement	DQ
P[Edge] [n-3]	A	True	DQ
	B	Complement	DQ
P[Edge] [n-2]	A	True	DQ
	B	Complement	DQ
P[Edge] [n-1]	A	True	DQ
P[Edge] [n]			
	B	Complement	DQ
P[Edge] [n+1]	A	True	[Edge]DQSn
	B	Complement	DQ
P[Edge] [n+2]	A	True	DQ
	B	Complement	DQ
P[Edge] [n+3]	A	True	DQ
	B	Complement	DQ

Notes:
1. “n” is a row/column PIC number.
2. The DDR interface is designed for memories that support one DQS strobe per eight bits of data. In some packages, all the potential DDR data (DQ) pins may not be available.
3. The definition of the PIC numbering is provided in the Signal Names column of the Signal Descriptions table in this data sheet.

LFXP3 & LFXP6 Logic Signal Connections: 208 PQFP

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
1	CFG1	0	-	-	CFG1	0	-	-
2	DONE	0	-	-	DONE	0	-	-
3	PROGRAMN	7	-	-	PROGRAMN	7	-	-
4	CCLK	7	-	-	CCLK	7	-	-
5	GND	-	-	-	GND	-	-	-
6	PL2A	7	T[3]	-	PL2A	7	T[3]	-
7	GNDIO7	7	-	-	GNDIO7	7	-	-
8	PL2B	7	C[3]	-	PL2B	7	C[3]	-
9	PL3A	7	T	LUM0_PLLT_FB_A	PL3A	7	T	LUM0_PLLT_FB_A
10	PL3B	7	C	LUM0_PLLC_FB_A	PL3B	7	C	LUM0_PLLC_FB_A
11	PL4A	7	T[3]	-	PL4A	7	T[3]	-
12	PL4B	7	C[3]	-	PL4B	7	C[3]	-
13	VCCIO7	7	-	-	VCCIO7	7	-	-
14	PL5A	7	-	VREF1_7	PL5A	7	-	VREF1_7
15	PL6B	7	-	VREF2_7	PL6B	7	-	VREF2_7
16	GNDIO7	7	-	-	GNDIO7	7	-	-
17	PL7A	7	T[3]	DQS	PL7A	7	T[3]	DQS
18	PL7B	7	C[3]	-	PL7B	7	C[3]	-
19	VCC	-	-	-	VCC	-	-	-
20	PL8A	7	T	LUM0_PLLT_IN_A	PL8A	7	T	LUM0_PLLT_IN_A
21	PL8B	7	C	LUM0_PLLC_IN_A	PL8B	7	C	LUM0_PLLC_IN_A
22	PL9A	7	T[3]	-	PL9A	7	T[3]	-
23	VCCIO7	7	-	-	VCCIO7	7	-	-
24	PL9B	7	C[3]	-	PL9B	7	C[3]	-
25	VCCP0	-	-	-	VCCP0	-	-	-
26	GNDP0	-	-	-	GNDP0	-	-	-
27	NC	-	-	-	PL15B	6	-	-
28	VCCIO6	6	-	-	VCCIO6	6	-	-
29	PL11A	6	T[3]	-	PL16A	6	T[3]	-
30	PL11B	6	C[3]	-	PL16B	6	C[3]	-
31	PL12A	6	T	PCLKT6_0	PL17A	6	T	PCLKT6_0
32	PL12B	6	C	PCLKC6_0	PL17B	6	C	PCLKC6_0
33	NC	-	-	-	PL18A	6	T[3]	-
34	NC	-	-	-	PL18B	6	C[3]	-
35	VCC	-	-	-	VCC	-	-	-
36	PL13A	6	T[3]	-	PL21A	6	T[3]	-
37	PL13B	6	C[3]	-	PL21B	6	C[3]	-
38	GNDIO6	6	-	-	GNDIO6	6	-	-
39	PL14A	6	-	VREF1_6	PL22A	6	-	VREF1_6
40	PL15B	6	-	VREF2_6	PL23B	6	-	VREF2_6
41	VCCIO6	6	-	-	VCCIO6	6	-	-
42	PL16A	6	T[3]	DQS	PL24A	6	T[3]	DQS
43	PL16B	6	C[3]	-	PL24B	6	C[3]	-
44	PL17A	6	T	-	PL25A	6	T	-
45	PL17B	6	C	-	PL25B	6	C	-
46	PL18A	6	T[3]	-	PL26A	6	T[3]	-

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
P16	PR37B	3	C[3]	-	PR41B	3	C[3]	-
R16	PR37A	3	T[3]	DQS	PR41A	3	T[3]	DQS
M15	PR36B	3	-	-	PR40B	3	-	-
N14	PR35A	3	-	VREF1_3	PR39A	3	-	VREF1_3
-	GNDIO3	3	-	-	GNDIO3	3	-	-
M14	PR33B	3	C	-	PR37B	3	C	-
L13	PR33A	3	T	-	PR37A	3	T	-
L15	PR32B	3	C[3]	-	PR36B	3	C[3]	-
L14	PR32A	3	T[3]	-	PR36A	3	T[3]	-
L12	PR30A	3	-	-	PR34A	3	-	-
M16	PR29B	3	C	RLM0_PLLC_IN_A	PR33B	3	C	RLM0_PLLC_IN_A
N16	PR29A	3	T	RLM0_PLLT_IN_A	PR33A	3	T	RLM0_PLLT_IN_A
-	GNDIO3	3	-	-	GNDIO3	3	-	-
K14	PR28B	3	C[3]	-	PR32B	3	C[3]	-
K15	PR28A	3	T[3]	DQS	PR32A	3	T[3]	DQS
K12	PR27B	3	-	-	PR31B	3	-	-
K13	PR26A	3	-	VREF2_3	PR30A	3	-	VREF2_3
L16	PR25B	3	C[3]	-	PR29B	3	C[3]	-
K16	PR25A	3	T[3]	-	PR29A	3	T[3]	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
J15	PR23B	3	C[3]	-	PR27B	3	C[3]	-
J14	PR23A	3	T[3]	-	PR27A	3	T[3]	-
J13	GNDP1	-	-	-	GNDP1	-	-	-
J12	VCCP1	-	-	-	VCCP1	-	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
J16	PR21B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0
H16	PR21A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0
H13	PR20B	2	C[3]	-	PR20B	2	C[3]	-
H12	PR20A	2	T[3]	DQS	PR20A	2	T[3]	DQS
H15	PR19B	2	-	-	PR19B	2	-	-
H14	PR18A	2	-	VREF1_2	PR18A	2	-	VREF1_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G15	PR17B	2	C[3]	-	PR17B	2	C[3]	-
G14	PR17A	2	T[3]	-	PR17A	2	T[3]	-
G16	PR16B	2	C	RUM0_PLLC_IN_A	PR16B	2	C	RUM0_PLLC_IN_A
F16	PR16A	2	T	RUM0_PLLT_IN_A	PR16A	2	T	RUM0_PLLT_IN_A
G13	PR15B	2	-	-	PR15B	2	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G12	PR12B	2	C	-	PR12B	2	C	-
F13	PR12A	2	T	-	PR12A	2	T	-
B16	PR11B	2	C[3]	-	PR11B	2	C[3]	-
C16	PR11A	2	T[3]	DQS	PR11A	2	T[3]	DQS

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

Ball Number	LFXP10				LFXP15				LFXP20			
	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
M21	VCCP1	-	-	-	VCCP1	-	-	-	VCCP1	-	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-	GNDIO2	2	-	-
M22	PR18B	2	C[3]	-	PR22B	2	C[3]	-	PR22B	2	C[3]	-
L22	PR18A	2	T[3]	-	PR22A	2	T[3]	-	PR22A	2	T[3]	-
K22	PR17B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0
K21	PR17A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0
L19	PR16B	2	C[3]	-	PR20B	2	C[3]	-	PR20B	2	C[3]	-
K20	PR16A	2	T[3]	DQS	PR20A	2	T[3]	DQS	PR20A	2	T[3]	DQS
L20	PR15B	2	-	-	PR19B	2	-	-	PR19B	2	-	-
L21	PR14A	2	-	VREF1_2	PR18A	2	-	VREF1_2	PR18A	2	-	VREF1_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-	GNDIO2	2	-	-
J22	PR13B	2	C[3]	-	PR17B	2	C[3]	-	PR17B	2	C[3]	-
J21	PR13A	2	T[3]	-	PR17A	2	T[3]	-	PR17A	2	T[3]	-
H22	PR12B	2	C	RUM0_PLLC_IN_A	PR16B	2	C	RUM0_PLLC_IN_A	PR16B	2	C	RUM0_PLLC_IN_A
H21	PR12A	2	T	RUM0_PLLT_IN_A	PR16A	2	T	RUM0_PLLT_IN_A	PR16A	2	T	RUM0_PLLT_IN_A
K19	PR11B	2	C[3]	-	PR15B	2	C[3]	-	PR15B	2	C[3]	-
J19	PR11A	2	T[3]	-	PR15A	2	T[3]	-	PR15A	2	T[3]	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-	GNDIO2	2	-	-
J20	PR9B	2	C[3]	-	PR13B	2	C[3]	-	PR13B	2	C[3]	-
H20	PR9A	2	T[3]	-	PR13A	2	T[3]	-	PR13A	2	T[3]	-
H19	PR8B	2	C	-	PR12B	2	C	-	PR12B	2	C	-
G19	PR8A	2	T	-	PR12A	2	T	-	PR12A	2	T	-
G22	PR7B	2	C[3]	-	PR11B	2	C[3]	-	PR11B	2	C[3]	-
G21	PR7A	2	T[3]	DQS	PR11A	2	T[3]	DQS	PR11A	2	T[3]	DQS
-	GNDIO2	2	-	-	GNDIO2	2	-	-	GNDIO2	2	-	-
F20	PR6B	2	-	-	PR10B	2	-	-	PR10B	2	-	-
G20	PR5A	2	-	VREF2_2	PR9A	2	-	VREF2_2	PR9A	2	-	VREF2_2
F22	PR4B	2	C[3]	-	PR8B	2	C[3]	-	PR8B	2	C[3]	-
F21	PR4A	2	T[3]	-	PR8A	2	T[3]	-	PR8A	2	T[3]	-
E22	PR3B	2	C	RUM0_PLLC_FB_A	PR7B	2	C	RUM0_PLLC_FB_A	PR7B	2	C	RUM0_PLLC_FB_A
E21	PR3A	2	T	RUM0_PLLT_FB_A	PR7A	2	T	RUM0_PLLT_FB_A	PR7A	2	T	RUM0_PLLT_FB_A
D22	PR2B	2	C[3]	-	PR6B	2	C[3]	-	PR6B	2	C[3]	-
D21	PR2A	2	T[3]	-	PR6A	2	T[3]	-	PR6A	2	T[3]	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-	GNDIO2	2	-	-
F19	TDO	-	-	-	TDO	-	-	-	TDO	-	-	-
E20	VCCJ	-	-	-	VCCJ	-	-	-	VCCJ	-	-	-
D20	TDI	-	-	-	TDI	-	-	-	TDI	-	-	-
D19	TMS	-	-	-	TMS	-	-	-	TMS	-	-	-
D18	TCK	-	-	-	TCK	-	-	-	TCK	-	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-	GNDIO1	1	-	-
E19	-	-	-	-	PT48A	1	-	-	PT52A	1	-	-
D17	-	-	-	-	PT47B	1	C	-	PT51B	1	C	-
D16	-	-	-	-	PT47A	1	T	DQS	PT51A	1	T	DQS
C16	-	-	-	-	PT46B	1	-	-	PT50B	1	-	-
C15	-	-	-	-	PT45A	1	-	-	PT49A	1	-	-
C17	-	-	-	-	PT44B	1	C	-	PT48B	1	C	-
C18	PT39A	1	-	-	PT44A	1	T	-	PT48A	1	T	-
C19	PT38B	1	C	-	PT43B	1	C	-	PT47B	1	C	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-	GNDIO1	1	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L1	-	-	-	-	PL23A	7	T[3]	-
M1	-	-	-	-	PL23B	7	C[3]	-
M2	-	-	-	-	PL24A	7	-	-
L5	VCCP0	-	-	-	VCCP0	-	-	-
N2	GNDP0	-	-	-	GNDP0	-	-	-
N1	-	-	-	-	PL25B	6	-	-
P2	-	-	-	-	PL26A	6	T[3]	-
P1	-	-	-	-	PL26B	6	C[3]	-
M4	PL23A	6	T[3]	-	PL27A	6	T[3]	-
M3	PL23B	6	C[3]	-	PL27B	6	C[3]	-
R2	PL24A	6	T	PCLKT6_0	PL28A	6	T	PCLKT6_0
-	GNDIO6	6	-	-	GNDIO6	6	-	-
R1	PL24B	6	C	PCLKC6_0	PL28B	6	C	PCLKC6_0
N3	PL25A	6	T[3]	-	PL29A	6	T[3]	-
N4	PL25B	6	C[3]	-	PL29B	6	C[3]	-
M5	PL26A	6	-	-	PL30A	6	-	-
N5	PL27B	6	-	VREF1_6	PL31B	6	-	VREF1_6
T2	PL28A	6	T[3]	DQS	PL32A	6	T[3]	DQS
T1	PL28B	6	C[3]	-	PL32B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
U2	PL29A	6	T	LLM0_PLLT_IN_A	PL33A	6	T	LLM0_PLLT_IN_A
U1	PL29B	6	C	LLM0_PLLC_IN_A	PL33B	6	C	LLM0_PLLC_IN_A
P3	PL30A	6	T[3]	-	PL34A	6	T[3]	-
P4	PL30B	6	C[3]	-	PL34B	6	C[3]	-
P6	PL32A	6	T[3]	-	PL36A	6	T[3]	-
P5	PL32B	6	C[3]	-	PL36B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
V2	PL33A	6	T	-	PL37A	6	T	-
V1	PL33B	6	C	-	PL37B	6	C	-
W2	PL34A	6	T[3]	-	PL38A	6	T[3]	-
W1	PL34B	6	C[3]	-	PL38B	6	C[3]	-
R3	PL35A	6	-	VREF2_6	PL39A	6	-	VREF2_6
R4	PL36B	6	-	-	PL40B	6	-	-
R6	PL37A	6	T[3]	DQS	PL41A	6	T[3]	DQS
R5	PL37B	6	C[3]	-	PL41B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
Y2	PL38A	6	T	LLM0_PLLT_FB_A	PL42A	6	T	LLM0_PLLT_FB_A
Y1	PL38B	6	C	LLM0_PLLC_FB_A	PL42B	6	C	LLM0_PLLC_FB_A
T3	PL39A	6	T[3]	-	PL43A	6	T[3]	-
T4	PL39B	6	C[3]	-	PL43B	6	C[3]	-
W3	PL40A	6	T[3]	-	PL44A	6	T[3]	-
V3	PL40B	6	C[3]	-	PL44B	6	C[3]	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
AB5	PB16A	5	T	-	PB20A	5	T	-
AB6	PB16B	5	C	-	PB20B	5	C	-
AA8	PB17A	5	T	-	PB21A	5	T	-
AA9	PB17B	5	C	VREF2_5	PB21B	5	C	VREF2_5
W10	PB18A	5	T	-	PB22A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
V10	PB18B	5	C	-	PB22B	5	C	-
AB7	PB19A	5	T	-	PB23A	5	T	-
AB8	PB19B	5	C	-	PB23B	5	C	-
AB9	PB20A	5	T	-	PB24A	5	T	-
AB10	PB20B	5	C	-	PB24B	5	C	-
Y10	PB21A	5	-	-	PB25A	5	-	-
AA10	PB22B	5	-	-	PB26B	5	-	-
W11	PB23A	5	T	DQS	PB27A	5	T	DQS
V11	PB23B	5	C	-	PB27B	5	C	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
Y11	PB24A	5	T	-	PB28A	5	T	-
AA11	PB24B	5	C	-	PB28B	5	C	-
AB11	PB25A	5	T	-	PB29A	5	T	-
AB12	PB25B	5	C	-	PB29B	5	C	-
Y12	PB26A	4	T	-	PB30A	4	T	-
AA12	PB26B	4	C	-	PB30B	4	C	-
W12	PB27A	4	T	PCLKT4_0	PB31A	4	T	PCLKT4_0
V12	PB27B	4	C	PCLKC4_0	PB31B	4	C	PCLKC4_0
-	GNDIO4	4	-	-	GNDIO4	4	-	-
AB13	PB28A	4	T	-	PB32A	4	T	-
AB14	PB28B	4	C	-	PB32B	4	C	-
AA13	PB29A	4	-	-	PB33A	4	-	-
Y13	PB30B	4	-	-	PB34B	4	-	-
AB15	PB31A	4	T	DQS	PB35A	4	T	DQS
AB16	PB31B	4	C	VREF1_4	PB35B	4	C	VREF1_4
V13	PB32A	4	T	-	PB36A	4	T	-
W13	PB32B	4	C	-	PB36B	4	C	-
AA14	PB33A	4	T	-	PB37A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
AA15	PB33B	4	C	-	PB37B	4	C	-
AB17	PB34A	4	T	-	PB38A	4	T	-
AB18	PB34B	4	C	-	PB38B	4	C	-
W14	PB35A	4	T	-	PB39A	4	T	-
Y14	PB35B	4	C	-	PB39B	4	C	-
U14	PB36A	4	T	VREF2_4	PB40A	4	T	VREF2_4
V14	PB36B	4	C	-	PB40B	4	C	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
B3	PT8B	0	C	-	PT12B	0	C	-
A3	PT8A	0	T	-	PT12A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
D7	PT7B	0	C	-	PT11B	0	C	-
C7	PT7A	0	T	DQS	PT11A	0	T	DQS
B2	PT6B	0	-	-	PT10B	0	-	-
C2	PT5A	0	-	-	PT9A	0	-	-
C3	PT4B	0	C	-	PT8B	0	C	-
D3	PT4A	0	T	-	PT8A	0	T	-
F7	PT3B	0	C	-	PT7B	0	C	-
E7	PT3A	0	T	-	PT7A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
C6	-	-	-	-	PT6B	0	C	-
D6	-	-	-	-	PT6A	0	T	-
C5	-	-	-	-	PT5B	0	C	-
C4	-	-	-	-	PT5A	0	T	-
F6	-	-	-	-	PT4B	0	C	-
E6	-	-	-	-	PT4A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
E4	-	-	-	-	PT3B	0	-	-
E5	CFG0	0	-	-	CFG0	0	-	-
D4	CFG1	0	-	-	CFG1	0	-	-
D5	DONE	0	-	-	DONE	0	-	-
A1	GND	-	-	-	GND	-	-	-
A2	GND	-	-	-	GND	-	-	-
A21	GND	-	-	-	GND	-	-	-
A22	GND	-	-	-	GND	-	-	-
AA1	GND	-	-	-	GND	-	-	-
AA22	GND	-	-	-	GND	-	-	-
AB1	GND	-	-	-	GND	-	-	-
AB2	GND	-	-	-	GND	-	-	-
AB21	GND	-	-	-	GND	-	-	-
AB22	GND	-	-	-	GND	-	-	-
B1	GND	-	-	-	GND	-	-	-
B22	GND	-	-	-	GND	-	-	-
H14	GND	-	-	-	GND	-	-	-
H9	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-
J11	GND	-	-	-	GND	-	-	-
J12	GND	-	-	-	GND	-	-	-
J13	GND	-	-	-	GND	-	-	-
J14	GND	-	-	-	GND	-	-	-

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1052 - Power Estimation and Management for LatticeECP/EC and LatticeXP Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

LatticeXP Family Data Sheet Supplemental Information

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For Further Information

A variety of technical notes for the LatticeXP family are available on the Lattice website at www.latticesemi.com.

- LatticeECP/EC and LatticeXP sysIO Usage Guide (TN1056)
- Lattice ispTRACY Usage Guide (TN1054)
- LatticeECP/EC and LatticeXP sysCLOCK PLL Design and Usage Guide (TN1049)
- Memory Usage Guide for LatticeECP/EC and LatticeXP Devices (TN1051)
- LatticeECP/EC and XP DDR Usage Guide (TN1050)
- Power Estimation and Management for LatticeECP/EC and LatticeXP Devices (TN1052)
- LatticeXP sysCONFIG Usage Guide (TN1082)

For further information on interface standards refer to the following web sites:

- JEDEC Standards (LVTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- PCI: www.pcisig.com